

MODEL: HSB03-121218 | **DESCRIPTION:** HEAT SINK**FEATURES**

- BGA design
- small footprint
- aluminum alloy
- black anodized finish

**MODEL**

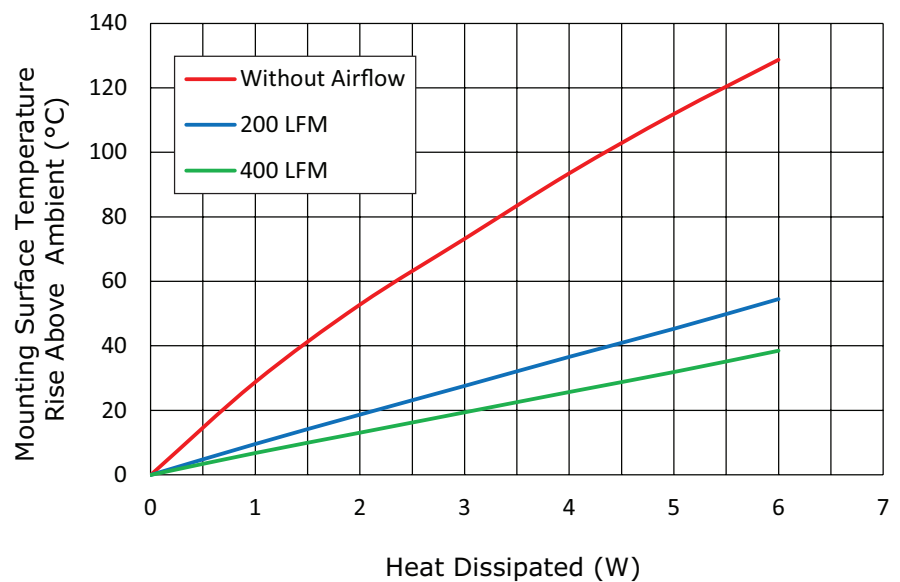
	thermal resistance ¹				power dissipation ¹ @ 75°C ΔT, nat conv [W]
	@ 75°C ΔT, nat conv [°C/W]	@ 1 W, nat conv [°C/W]	@ 1 W, 200 LFM [°C/W]	@ 1 W, 400 LFM [°C/W]	
HSB03-121218	24.01	28.8	9.6	6.8	3.12

Note: 1. See performance curves for full thermal resistance details.

PERFORMANCE CURVES

Power [W]	Heatsink Temperature Rise Above Ambient (ΔT = T _{hs} - T _a) [°C]		
	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	28.8	9.6	6.8
2	52.8	18.7	13.1
3	73.2	27.6	19.4
4	93.5	36.6	25.7
5	111.9	45.3	31.9
6	128.7	54.5	38.5

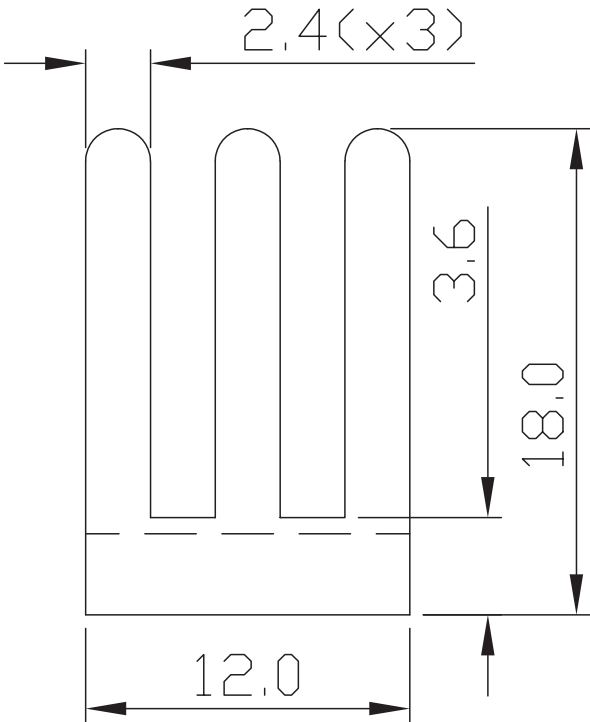
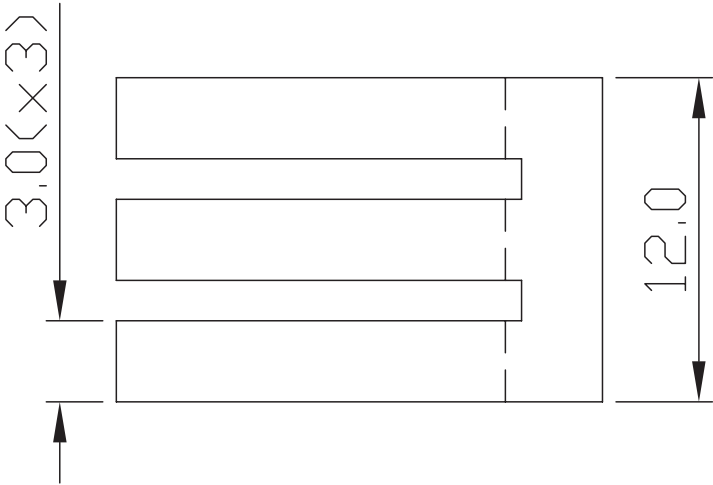
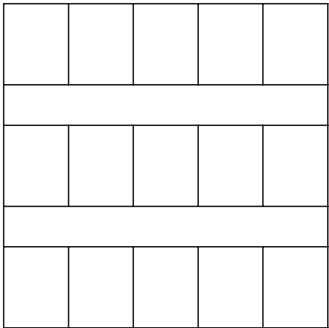
T_{hs}: "hot spot" temperature measured on the heatsink
T_a: ambient temperature



MECHANICAL DRAWING

units: mm
tolerance: ±0.38 mm

MATERIAL	AL 6063-T5
FINISH	black anodized
WEIGHT	3.8 g



REVISION HISTORY

rev.	description	date
1.0	initial release	06/24/2021
1.01	logo, datasheet style update	08/05/2022

The revision history provided is for informational purposes only and is believed to be accurate.



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